Form No: T00119-1-0000-TBM02-170300101

Specification for Approval

Date: 2018/06/18

Customer :

TAI-TECH P/N: WCM0805M801-2-CM

CUSTOMER P/N:

DESCRIPTION:

QUANTITY: pcs

REMARK:		
Customer Approval Feedback		

西北臺慶科技股份有限公司
TAI-TECH Advanced Electronics Co., Ltd

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APPROVED	CHECKED	DRAWN
楊祥忠 Mike Yang	林志鴻 Zhi-Hong Lin	張展耀 Kevin Chang

Wire Wound Type Common Mode Filter

WCM0805M801-2-CM

ECN HISTORY LIST

REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	17/03/02	新 發 行	楊祥忠	林志鴻	張展耀
備註					

Wire Wound Type Common Mode Filter

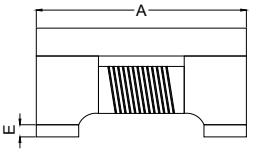
WCM0805M801-2-CM

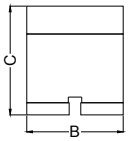
1.Features

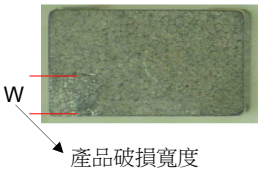
1. High common mode impedance at high frequency cause excellent noise suppression performance.
2. WCM0805 series realizes small size and low profile.
3. 100% Lead(Pb) & Halogen-Free and RoHS compliant.

Halogen-free Pb-free

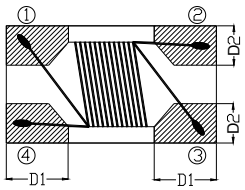
2.Dimension







當破損面積＜5%,產品列入允收品範圍



Series	A(mm)	B(mm)	C(mm)	D1(mm)	D2(mm)	E(mm)
0805	2.0±0.2	1.2±0.2	1.2±0.2	0.50±0.1	0.51±0.1	0.15±0.1

3.Part Numbering

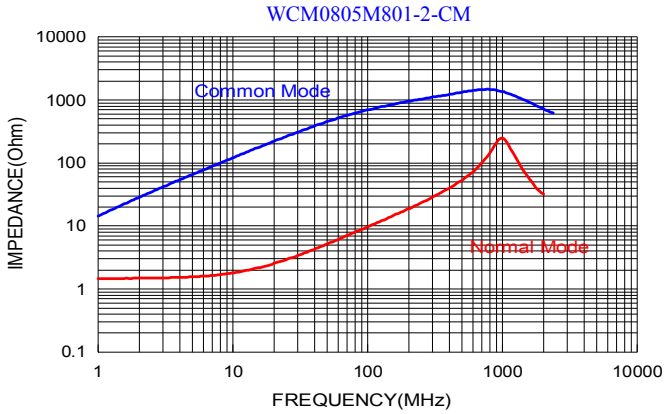
WCM	0805	M	801	-	2	-	CM
A	B	C	D		E		F

A: Series
B: Dimension
C: Material Ferrite Core
D: Impedance 801=800Ω
E: Number of Lines 2=2 lines
F: Category Code

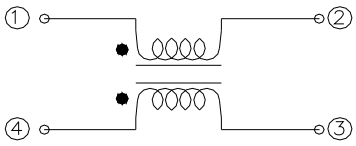
4.Specification

TAI-TECH Part Number	Common mode Impedance (Ω)	Test Frequency (MHz)	DC Resistance (Ω) max.	Rated Current (mA)max.	Rated Volt. (Vdc)max.
WCM0805M801-2-CM	800±25%	100	1	300	50

Typical Impedance v.s. Frequency Curve

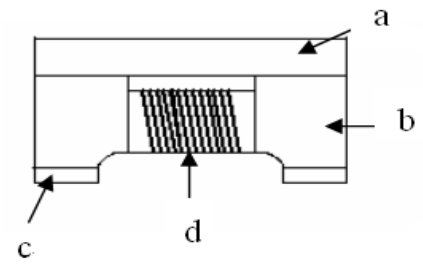


5.Schematic Diagram



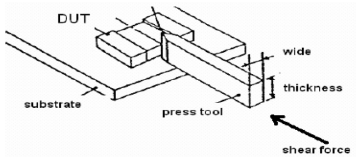
6. Materials

No.	Description	Specification
a.	Upper Plate	Ferrite
b.	Core	Ferrite Core
c	Termination	Tin (Pb Free)
d	Wire	Enameled Copper Wire



7.Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	-40~+125℃ (on board)	
Electrical Performance Test		
Z(common mode)	Refer to standard electrical characteristics list.	Agilent-4291A+ Agilent -16197A
DCR		Agilent-4338B
I.R.		Agilent4339
Temperature Rise Test	Rated Current < 1A ΔT 20℃Max Rated Current ≧ 1A ΔT 40℃Max	1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer
Reliability Test		
Life Test	Appearance：No damage. Inductance：within±10% of initial value Impedance：within±15% of initial value RDC：within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature：125±2℃ Applied current：rated current Duration：1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity：85±2 ％ R.H, Temperature：85℃±2℃ Duration：1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs,keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1：-40±2℃ 30±5min Step2：25±2℃ ≦0.5min Step3：125±2℃ 30±5min Number of cycles： 500 Measured at room temperature after placing for 24±2 hrs
Vibration		Oscillation Frequency: 10～2K～10Hz for 20 minutes Equipment： Vibration checker Total Amplitude:1.52mm±10% Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)。

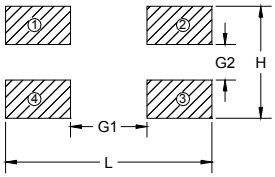
<table>
<tr><th>Item</th><th>Performance</th><th>Test Condition</th></tr>
<tr><td>Shock</td><td rowspan="2">Appearance：No damage.
Inductance：within±10% of initial value
Impedance：within±15% of initial value
RDC：within ±15% of initial value and shall not exceed the specification value</td><td>
<table>
<tr><th>Type</th><th>Peak value (g' s)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr>
<tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
<tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
</table>
shocks in each direction along 3 perpendicular axes.
</td></tr>
<tr><td>Bending</td><td>Shall be mounted on a FR4 substrate of the following dimensions: >=0805:40x100x1.2mm <0805:40x100x0.8mm
Bending depth:
>=0805inch(2012mm):1.2mm
<0805 inch(2012mm):0.8mm
duration of 10 sec.</td></tr>
<tr><td>Soderability</td><td>More than 95% of the terminal electrode should be covered with solder。</td><td>Preheat: 150℃,60sec.。
Solder: Sn96.5% Ag3% Cu0.5%
Temperature: 245±5℃。
Flux for lead free: Rosin. 9.5%。
Dip time: 4±1sec。
Depth: completely cover the termination</td></tr>
<tr><td>Resistance to Soldering Heat</td><td rowspan="2">Appearance：No damage.
Inductance：within±10% of initial value
Impedance：within±15% of initial value
RDC：within ±15% of initial value and shall not exceed the specification value</td><td>Number of heat cycles: 1
<table>
<tr><td>Temperature (°C)</td><td>Time(s)</td><td>Temperature ramp/immersion and emersion rate</td></tr>
<tr><td>260 ±5(solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td></tr>
</table>
</td></tr>
<tr><td>Terminal Strength</td><td>Preconditioning:Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles
With the component mounted on a PCB with the device to be tested, apply a force (>0805 inch(2012mm):1kg , <=0805 inch(2012mm):0.5kg)to the side of a device being tested.
This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.
 

</td></tr>
</table>

8.Soldering and Mounting

8-1. Recommended PC Board Pattern

	WCM0805
L(mm)	2.60
H(mm)	1.40
G1(mm)	1.25
G2(mm)	0.45



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.
Products shall be positioned in the sideway direction to against the mechanical stress to prevent failure.

8-2. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for all wave and re-flow soldering systems.
If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

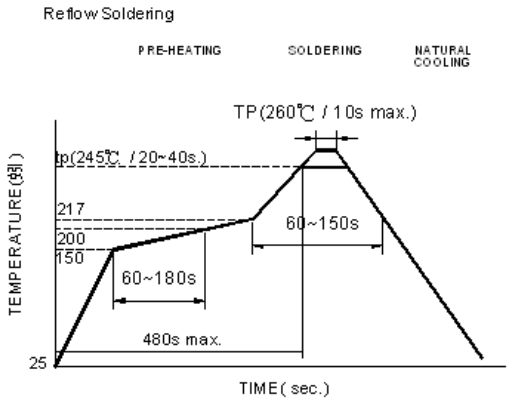
8-2.1 Lead Free Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

8-2.2 Soldering Iron(Figure 2):

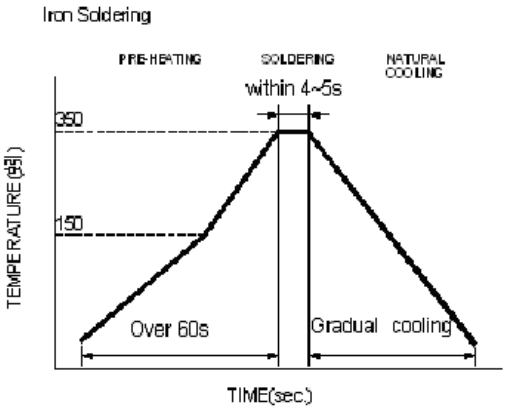
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Preheat circuit and products to 150℃
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355℃ tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5 sec.



Reflow times: 3 times max.

Fig.1

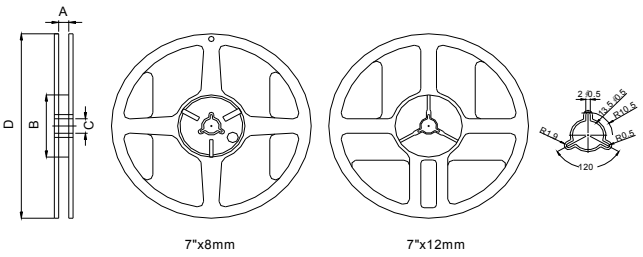


Iron Soldering times: 1 times max.

Fig.2

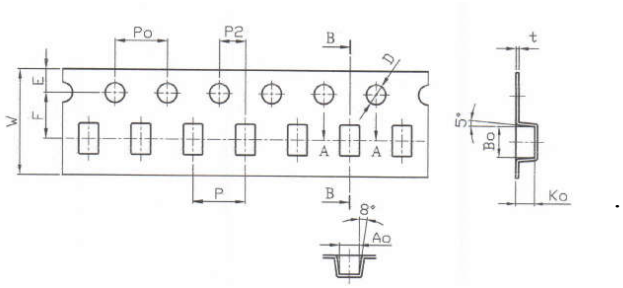
9.Packaging Information

9-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2

9-2. Tape Dimension / 8mm

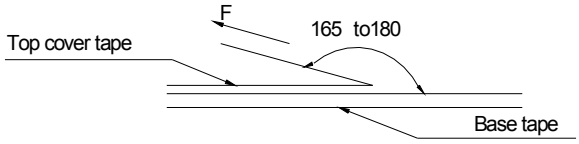


Series	W(mm)	P(mm)	E(mm)	F(mm)	P2(mm)	D(mm)	P0(mm)	A0(mm)	B0(mm)	K0(mm)	t(mm)
WCM0805	8.00±0.10	4.00±0.10	1.75±0.10	3.50±0.05	2.00±0.05	1.50+0.10/-0.00	4.00±0.10	1.50±0.10	2.35±0.10	1.45±0.10	0.28±0.05

9-3. Packaging Quantity

Chip size	Chip/Reel	Inner Box	Middle Box	Carton
WCM0805	2000	10000	50000	100000

9-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice

- Storage Conditions
  To maintain the solderability of terminal electrodes:
  1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
  2. Temperature and humidity conditions: Less than 40℃ and 60% RH.
  3. Recommended products should be used within 12 months form the time of delivery.
  4. The packaging material should be kept where no chlorine or sulfur exists in the air.

- Transportation
  1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

单击下面可查看定价，库存，交付和生命周期等信息

>>TAI-TECH(台庆)